Quik-Pak Installs New QFN Production Line in San Diego

Microelectronic Packaging and Assembly Solutions Provider Exhibits at IMAPS 2017 International Symposium Oct. 10-11, Raleigh, NC, Booth 210

San Diego, CA – October 10, 2017 – Quik-Pak, a provider of innovative microelectronic packaging and assembly solutions, has installed a new production line for Overmolded QFN Packages at its San Diego facility. The addition of a K&S IConn Plus wirebonder, molding press and laser marker onsite allows the company to package devices quickly. This enables its customers to more rapidly validate their designs and accelerate time to market.

“We’ve seen steady growth for die packaging in the QFN platform. It has become the package of choice for single die, multi-die, SiPs and stacked die,” said Quik-Pak Global Sales and Marketing Director Casey Krawiec. “Having a production line onsite in San Diego enables us to expedite packaging for quick-turn engineering builds and offer an alternative to going offshore for high-volume production.”

Quik-Pak’s overmolded, open-tooled QFN and DFN packages are designed for quick-turn engineering builds, with standard five-day delivery of assembled QFNs. Custom designs will be available in as little as five weeks after drawing approval. The QFNs are available in over 35 designs, with multiple thicknesses. Package sizes range from 2x2 mm to 12x12 mm for QFNs and 1.5x1.5 mm to 4x4 mm for DFNs. All QFNs are RoHS compliant and utilize NiPdAu-plated lead frames.

Quik-Pak recently had an independent third-party laboratory confirm two overmolded packages from the line (4x4mm QFN24 and 6x6mm QFN48) passed MSL3 level criteria for delamination and cracking per IPC/JEDEC-J-STD-020E.

Quik-Pak will officially introduce its new production services in Booth 210 at the IMAPS 2017 International Symposium on Microelectronics in Raleigh, North Carolina, October 10-11, 2017. Quik-Pak and its parent company Promex are Corporate Premier Members of IMAPS. In addition, last year Quik-Pak received the IMAPS Corporate Recognition Award for Significant Technical Contributions to the Microelectronics Industry.

ABOUT QUIK-PAK

Quik-Pak, a division of Promex, provides IC packaging, assembly and wafer preparation services in its ISO 9001:2008-certified, ITAR-registered facility in San Diego, California. The company’s overmolded QFN/DFN packages and premolded air cavity QFN packages provide a fast, convenient solution for prototype to full production needs. Same-day assembly services are provided to reduce time to market. More information is available at http://www.icproto.com or by calling 858-674-4676.

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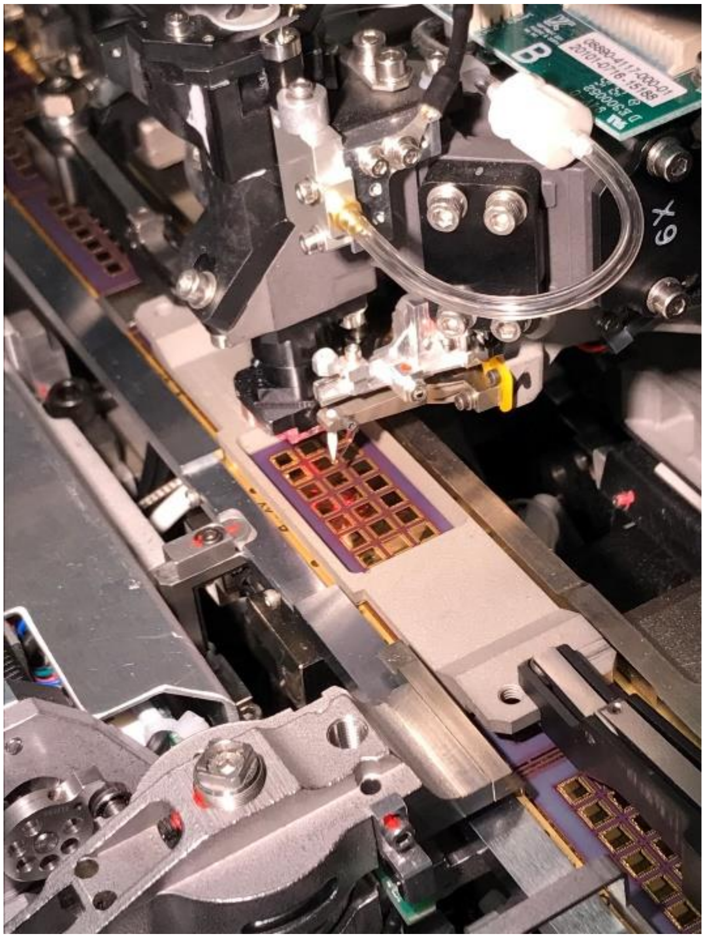
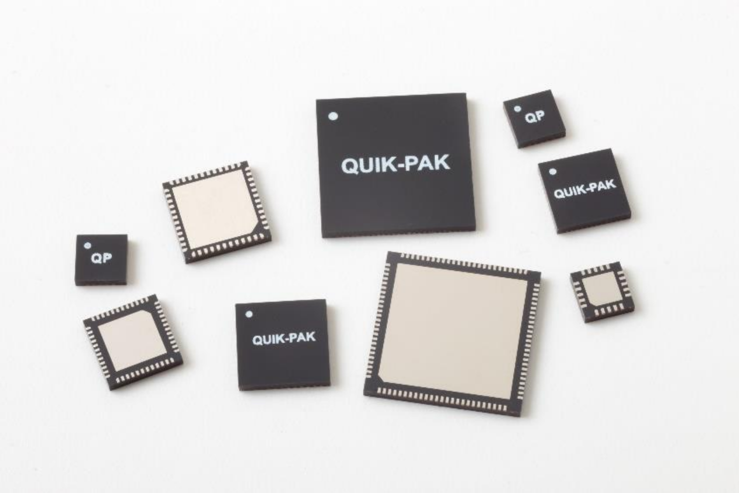


Prototype QFN lead frames being wire bonded on Quik-Pak's new K&S IConn Plus Wire Bonder onsite in San Diego, CA. The overmolded, open-tooled QFN and DFN packages are designed for quick-turn engineering builds, with standard five-day delivery of assembled QFNs. Quik-Pak's QFNs are available in over 35 designs, with multiple thicknesses. Package sizes range from 2x2 mm to 12x12mm for QFNs and 1.5x1.5mm to 4x4 mm for DFNs. All QFNs are RoHS compliant and utilize NiPdAu-plated lead frames.



Quik-Pak's overmolded, open-tooled QFN and DFN packages are designed for quick-turn engineering builds, with standard five-day delivery of assembled QFNs. The QFNs are produced onsite in San Diego and are available in over 35 designs, with multiple thicknesses. Package sizes range from 2x2 mm to 12x12 mm for QFNs and 1.5x1.5 mm to 4x4 mm for DFNs. All QFNs are RoHS compliant and utilize NiPdAu-plated lead frames.